

Title (en)
BINDER RESIN, VEHICLE COMPOSITION, AND PASTE COMPOSITION HAVING INORGANIC MICROPARTICLE DISPERSED THEREIN

Title (de)
BINDEMITTELHARZ, VEHIKELZUSAMMENSETZUNG UND PASTENZUSAMMENSETZUNG MIT DARIN DISPERGIERTEM ANORGANISCHEM MIKROPARTIKEL

Title (fr)
RÉSINE LIANTE, COMPOSITION DE VÉHICULE ET COMPOSITION DE PÂTE AYANT DES MICROPARTICULES INORGANIQUES DISPERSÉES DANS CELLE-CI

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Abstract (en)
It is an object of the present invention to provide a binder resin which, when used in an inorganic fine particle-dispersed paste composition, leaves little amount of residual carbon after sintering and can be degreased even under low temperature conditions. It is also an object of the present invention to provide a vehicle composition and an inorganic fine particle-dispersed paste composition, which are obtained by using the binder resin. The binder resin of the present invention is for use in an inorganic fine particle-dispersed paste composition containing inorganic fine particles. The binder resin contains from 5 to 55% by weight of a segment derived from methyl methacrylate, from 30 to 80% by weight of a segment derived from isobutyl methacrylate, and from 5 to 20% by weight of a segment derived from polyoxyalkylene ether monomethacrylate.

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